

MECHANICAL CASE OUTLINE

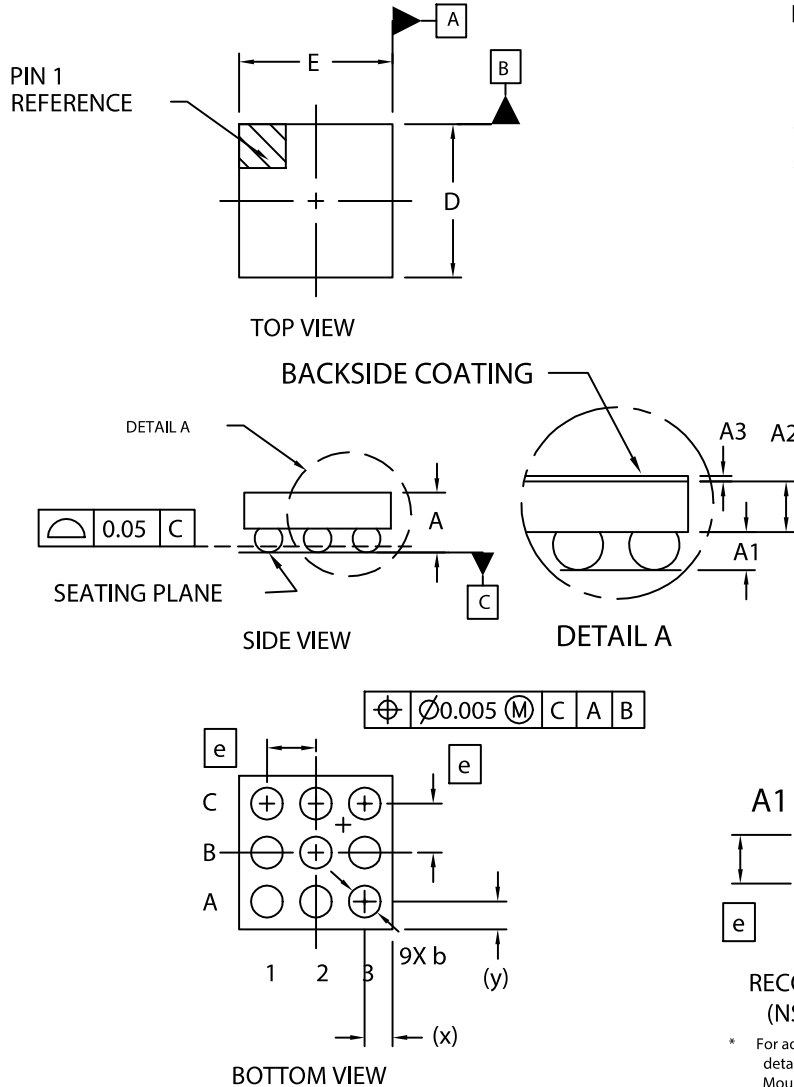
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP9 1.22x1.22x0.581
CASE 567SU
ISSUE A

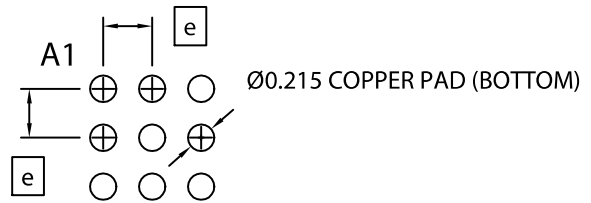
DATE 22 APR 2020



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN. | NOM. | MAX. |
| A | 0.543 | 0.581 | 0.619 |
| A1 | 0.183 | 0.203 | 0.223 |
| A2 | 0.338 | 0.353 | 0.368 |
| A3 | 0.022 | 0.025 | 0.028 |
| b | 0.240 | 0.260 | 0.280 |
| D | 1.19 | 1.22 | 1.25 |
| E | 1.19 | 1.22 | 1.25 |
| e | 0.40 BSC | | |
| x | 0.195 | 0.210 | 0.225 |
| y | 0.195 | 0.210 | 0.225 |



**RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)**

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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